**WS-446-AL** Ball-Attach Flux

### Features
- Flux rheology applicable for all sphere sizes
- Suitable for Pb-free or Sn/Pb applications
- Uniform pin transfer over extended periods
- Red color for ease of detection
- Proven high yields in ball-attach process
- Excellent solderability on a wide range of surfaces

### Properties

<table>
<thead>
<tr>
<th>Flux Type Classification</th>
<th>Value</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)</td>
<td></td>
<td></td>
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<tr>
<td>Typical Viscosity</td>
<td>16kcps</td>
<td>Brookfield HB DVII+-CP (5rpm)</td>
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<tr>
<td>SIR (Ohms, after cleaning)</td>
<td>Pass (&gt;10^8 after 7 days @ 85°C and 85% RH)</td>
<td>J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)</td>
</tr>
<tr>
<td>Typical Acid Value</td>
<td>78mg KOH/g</td>
<td>Titration</td>
</tr>
<tr>
<td>Typical Tack Strength</td>
<td>180g</td>
<td>J-STD-005 (IPC-TM-650: 2.4.44)</td>
</tr>
<tr>
<td>Shelf Life</td>
<td>6 months (20–5°C)</td>
<td>Viscosity change/ microscope examination</td>
</tr>
</tbody>
</table>

All information is for reference only. Not to be used as incoming product specifications.

### Application
The amount of flux deposited on the substrate can be optimized by changing equipment parameters. Key variables include pin shape, pin diameter, shear speed, dwell, and depth of immersion. The flux rheology can be optimized for the desired application by shearing to achieve the desired viscosity.

### Cleaning
**WS-446-AL** residue can be cleaned with DI water, or water with an added cleaner. Ideal conditions for spray-cleaning: 25°C (room temperature) or higher for >1 minute at >60psi.

### Packaging
**WS-446-AL** is available in (10) 150g syringes and in 100g jars or cartridges. Other packaging can be provided to meet the customer’s specific requirements.

### Storage
For maximum shelf life **WS-446-AL** syringes and cartridges should be stored tip down. Storage temperatures should not exceed 30°C. After removing from cold storage, **WS-446-AL** should be allowed to stand for at least 4 hours at room temperature before using.
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Technical Support
Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation’s team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets
The SDS for this product is available by contacting askus@indium.com

Reflow
Recommended Profile:

Peak reflow temperature should be <350°C in an air or nitrogen atmosphere (<500ppm O₂), with a linear ramp up to 30°C above liquidus temperature. These profiles are recommended to the user as starting points, and should be optimized by the user to meet their individual process needs.